

Average Weight: 3.9000g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (Grams)	Component Percent of Total
Silicon Die					0.08304	2.129%
	Silicon	7440-21-3	100.00		0.08304	
Die Attach Material					0.012939	0.332%
	Polymetric material	Proprietary	3.00		0.000388	
	Di-Ester resin	Proprietary	7.50		0.000970	
	Functionalized ester	Proprietary	3.00		0.000388	
	Silver	7440-22-4	86.50		0.011192	
Mold Compound					1.79122	45.929%
	Solid epoxy resin	Trade secret	5.00		0.089561	
	Phenol resin	Trade secret	5.00		0.089561	
	Fused silica	60676-86-0	83.00		1.486711	
	Metal hydro oxide	Trade secret	1.00		0.017912	
	Carbon black	1333-86-4	1.00		0.017912	
	Crystalline silica	14808-60-7	5.00		0.89561	
Substrate					0.883503	22.654%
	Copper	7440-50-8	46.27	Metal layer	0.408797	
	Nickel	7440-02-0	0.60	Metal layer	0.005301	
	Gold	7440-57-5	0.13	Metal layer	0.001149	
	Glass fiber (GF)	N/A	23.00		0.203206	
	Flame retardant	N/A	3.20		0.028272	
	BT (core) HL-832NX	N/A	16.80		0.148429	
	Solder mask (EP)	N/A	10.00		0.088350	
Gold Wire					0.019700	0.505%
	Gold	7440-57-5	99.05		0.019512	
	Palladium	7440-05-3	0.95		0.000187	
	Beryllium	7440-41-7	0.00	Trace	0.0000003	
	Calcium	7440-70-2	0.00	Trace	0.0000004	
Solder Balls					1.109600	28.451%
	Tin	7440-31-5	63.00		0.699048	
	Lead	2425-79-8	37.00		0.410552	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
12/07/09	1.0	Initial Xilinx release.

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